

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1 11. (original): A method for fabricating a magnetic head, comprising the steps of:
2 fabricating a read head upon a substrate;
3 fabricating a P1 pole upon said read head;
4 fabricating a write gap layer upon said P1 pole;
5 fabricating a block of material upon said write gap layer, said block of material having a
6 sidewall disposed proximate a P2 pole tip location;
7 fabricating a seed layer upon said sidewall;
8 electroplating P2 pole tip material upon said seed layer, whereby a P2 pole tip is formed
9 having a width W that is comprised of a thickness of said seed layer material and a thickness of
10 said electroplated material;
11 fabricating an induction coil proximate said P2 pole tip;
12 fabricating a P3 pole above said induction coil in magnetic interconnection with said P2
13 pole tip; and
14 fabricating an encapsulation layer above said P3 pole.

1 12. (original): A method for fabricating a magnetic head as described in claim 11 wherein
2 said seed layer is fabricated to a thickness of approximately 50 Å to approximately 500 Å.

1 13. (original): A method for fabricating a magnetic head as described in claim 11 wherein
2 said electroplated material is fabricated to a thickness of approximately 100 Å to approximately
3 5000 Å.

1 14. (original): A method for fabricating a magnetic head as described in claim 11 wherein
2 said seed layer is fabricated to a thickness of approximately 50 Å to approximately 500 Å, and
3 wherein said electroplated material is fabricated to a thickness of approximately 100 Å to
4 approximately 5000 Å.

1 15. (original): A method for fabricating a magnetic head as described in claim 14 wherein
2 said seed layer is fabricated to a thickness of approximately 250 Å and said electroplated
3 material is fabricated to a thickness of approximately 1500 Å.

1 16. (original): A method for fabricating a magnetic head as described in claim 11 wherein
2 said P2 pole tip is fabricated within a P2 pole tip trench having width that is wider than said
3 width W of said P2 pole tip.

1 17. (original): A method for fabricating a magnetic head as described in claim 11 wherein
2 said block of material is removed from said write gap layer following said electroplating of said
3 P2 pole tip material, and said P1 pole is notched in an ion milling step.

1 18. (original): A method for fabricating a magnetic head as described in claim 14, wherein
2 said seed layer is comprised of NiFe and said P2 pole tip material that is electroplated upon said
3 seed layer is comprised of NiFe.

1 19. (new): A method for fabricating a magnetic head as described in claim 11, wherein said
2 sidewall comprises a planar surface that is disposed perpendicularly to said write gap layer.